

**In the Claims:**

Please cancel claim 7.

Please amend claim 2 as set forth below in the "Listing of Claims":

**LISTING OF CLAIMS**

Claim 1 (Canceled)

Claim 2 (Currently Amended): An epoxy resin composition for encapsulation of semiconductors which comprises (A) a spherical alumina, (B) an ultrafine silica having a specific surface area of 120-280 m<sup>2</sup>/g, (C) a silicone compound, (D) an epoxy resin, (E) a phenolic resin curing agent, and (F) a curing accelerator, said ultrafine silica being contained in an amount of 0.2-0.8% by weight based on the total weight of the resin composition,

wherein said silicone compound (C) is a polyorganosiloxane and is present in an amount of from 0.3 to 2.0% by weight based on the total weight of the resin composition, and

wherein the spherical alumina is present in an amount of from 85% to 92% by weight based on the total weight of the resin composition.

Claim 3 (Canceled)

Claim 4 (Withdrawn): A semiconductor apparatus in which a semiconductor element is mounted on one side of a substrate and substantially only the one side of the substrate on which the semiconductor element is mounted is encapsulated with the epoxy resin composition for semiconductor encapsulation of claim 2.

**Claim 5 (Canceled)**

**Claim 6 (Withdrawn):** A method of encapsulating a semiconductor apparatus having a semiconductor element mounted on one side of a substrate, comprising encapsulating substantially only the one side of the substrate on which the semiconductor element is mounted with the epoxy resin composition of claim 2.

**Claim 7 (Canceled)**